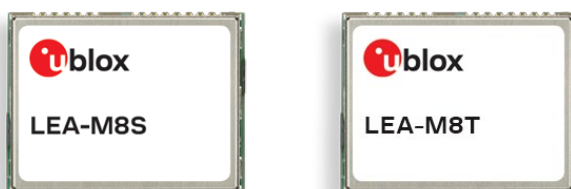


LEA-M8S / LEA-M8T

u-blox M8 concurrent GNSS modules

Hardware integration manual



Abstract

This document describes the features and specifications of u-blox LEA-M8S and LEA-M8T modules.

Document information

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This document applies to the following products:

Product name	Type number	Firmware version	PCN reference
LEA-M8S	LEA-M8S-0-10	ROM SPG 3.01	UBX-16012752
LEA-M8T	LEA-M8T-0-10	Flash FW 3.01 TIM 1.10	UBX-16004907
LEA-M8T	LEA-M8T-1-01	Flash FW 3.01 TIM 1.12	UBX-23001089

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1 Hardware description

1.1 Overview

LEA-M8S and LEA-M8T are concurrent GNSS positioning modules featuring the high performance u-blox M8 positioning engine. They are easy to integrate and combine exceptional positioning performance with highly flexible power, design, and connectivity options. SMT pads allow fully automated assembly with standard pick-and-place and reflow-soldering equipment for cost-efficient, high-volume production enabling short time-to-market.

-  For specific product features, see LEA-M8S Data sheet [1] and NEO / LEA-M8T Data sheet [2].
-  To determine which u-blox product best meets your needs, see the product selector tables on the u-blox website.

1.2 Configuration



The configuration settings can be modified using UBX protocol configuration messages, for more information see the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3]. The modified settings remain effective until power-down or reset. If these settings have been stored in Battery Backed RAM (BBR), the modified configuration will be retained, as long as the backup battery supply is not interrupted.

1.3 Connecting power

The LEA-M8S and LEA-M8T positioning modules have up to three power supply pins: **VCC**, **V_BCKP** and **VDD_USB**.


1.3.1 VCC: Main supply voltage



The **VCC** pin provides the main supply voltage. During operation, the current drawn by the module can vary by some orders of magnitude, especially if enabling low-power operation modes. For this reason, it is important that the supply circuitry is able to support the peak power for a short time (see the LEA-M8S Data sheet [1] and the NEO / LEA-M8T Data sheet **Error! Reference source not found.** for detailed specifications).

-  When switching from backup mode to normal operation or at start-up, the LEA-M8S and LEA-M8T modules must charge the internal capacitors in the core domain. In certain situations, this can result in a significant current draw. For low-power applications using power save and backup modes, it is important that the power supply or low ESR capacitors at the module input can deliver this current/charge.
-  Use a proper GND concept. Do not use any resistors or coils in the power line.

1.3.2 V_BCKP: Backup supply voltage

If the module supply has a power failure, the **V_BCKP** pin supplies the real-time clock (RTC) and battery-backed RAM (BBR). Use of valid time and the GNSS orbit data at start-up will improve the GNSS performance, that is, it enables hot and warm starts. If no backup battery is connected, the module performs a cold start at power-up.

-  Avoid high resistance on the **V_BCKP** line: During the switch from main supply to backup supply, a short current adjustment peak can cause high voltage drop on the pin with possible malfunctions.

-  If no backup supply voltage is available, connect the **V_BCKP** pin to **VCC**.
-  As long as the LEA-M8S and LEA-M8T modules are supplied via the **VCC**, the backup battery is disconnected from the RTC and the BBR to avoid unnecessary battery drain (see Figure 1). In this case, **VCC** supplies power to the RTC and BBR.

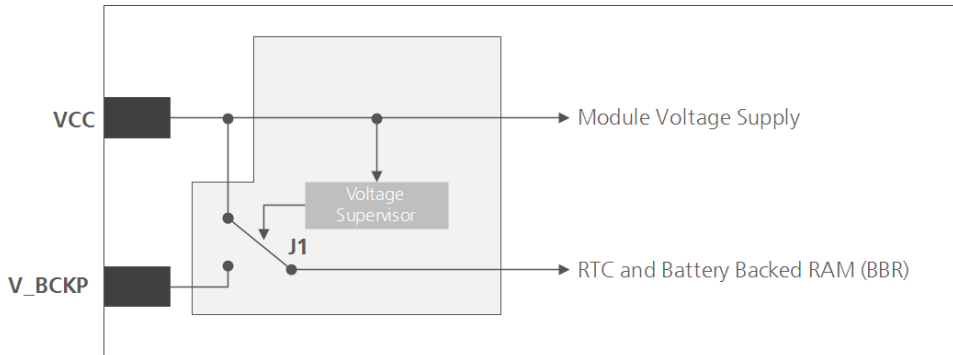


Figure 1: Backup battery and voltage (for exact pin orientation, see the LEA-M8S Data sheet [1] and the NEO/LEA-M8T Data sheet [2])

1.3.3 VDD_USB: USB interface power supply

VDD_USB supplies the USB interface. If the USB interface is not used, the **VDD_USB** pin must be connected to GND. For more information about correctly handling the **VDD_USB** pin, see section 1.4.

1.3.4 VCC_RF: Output voltage RF section

The **VCC_RF** pin can supply an active antenna or external LNA. For more information, see section 2.4.

1.3.5 V_ANT: Antenna supply

The **V_ANT** pin is available to provide antenna bias voltage to supply an optional external active antenna. For more information, see section 2.4.

-  If not used, connect the **V_ANT** pin to GND.

1.4 Interfaces

1.4.1 UART

The LEA-M8S and LEA-M8T positioning modules include a universal asynchronous receiver transmitter (UART) serial interface **RXD/TXD**, which supports configurable baud rates. The baud rates supported are specified in the LEA-M8S Data sheet [1] and the NEO / LEA-M8T Data sheet [2]. The signal output and input levels are 0 V to **VCC**. An interface based on RS232 standard levels (+/- 12 V) can be implemented using level shifters such as Maxim MAX3232. Hardware handshake signals and synchronous operation are not supported.

1.4.2 USB

A USB version 2.0 FS (full speed, 12 Mb/s) compatible interface is available for communication as an alternative to the UART. The **USB_DP** integrates a pull-up resistor to signal a full-speed device to the host. The **VDD_USB** pin supplies the USB interface.

u-blox provides Microsoft® certified USB drivers for Windows Vista, Windows 7, Windows 8 and Windows 10 operating systems. These drivers are available at our website at www.u-blox.com.

USB external components

The USB interface requires some external components to implement the physical characteristics required by the USB 2.0 specification. These external components are shown in Figure 2 and listed in Table 1. To comply with USB specifications, VBUS must be connected through an LDO (U1) to pin **VDD_USB** on the module.

The USB device is **self-powered**, the power supply (VCC) can be turned off and the digital block is not powered. In this case, since VBUS is still available, the USB host still receives the signal indicating that the device is present and ready to communicate. This should be avoided by disabling the LDO (U1) using the enable signal (EN) of the VCC-LDO or the output of a voltage supervisor. Depending on the characteristics of the LDO (U1), it is recommended to add a pull-down resistor (R11) at its output to ensure VDD_USB is not floating if the LDO (U1) is disabled or the USB cable is not connected, that is, VBUS is not supplied.

USB **bus powered** is not supported.

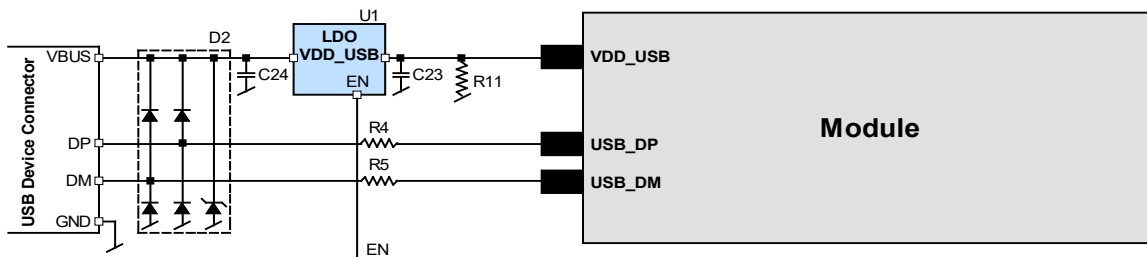


Figure 2: USB interface

Name	Component	Function	Comments
U1	LDO	Regulates VBUS (4.4 ... 5.25 V) down to a voltage of 3.3 V.	Almost no current requirement (~1 mA).
C23, C24	Capacitors		Required according to the specification of LDO U1.
D2	Protection diodes	Protect circuit from overvoltage / ESD when connecting.	Use low capacitance ESD protection such as ST Microelectronics USBLC6-2.
R4, R5	Serial termination resistors	Establish a full-speed driver impedance of 28 ... 44 Ω	A value of 27 Ω is recommended.
R11	Resistor		100 k Ω is recommended for USB self-powered setup. For bus-powered setup, R11 can be ignored.

Table 1: Summary of USB external components

1.4.3 Display data channel (DDC)


An I2C-compatible display data channel (DDC) interface is available for serial communication with an external host CPU. The interface only supports operation in slave mode (master mode is not supported). The DDC protocol and electrical interface are fully compatible with the fast mode of the I2C industry standard. DDC pins **SDA** and **SCL** have internal pull-up resistors.

For more information about the DDC implementation, see the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3]. For bandwidth information, see the LEA-M8S Data sheet [1] and the NEO / LEA-M8T Data sheet [2]. For timing parameters, consult the I2C-bus specification [6].

The u-blox M8 DDC interface supports serial communication with most u-blox cellular modules. See the specification of the applicable cellular module to confirm compatibility.


1.4.4 SPI (LEA-M8T only)

An SPI interface is available for communication to a host CPU.

 SPI is not available in the default configuration because its pins are shared with the UART and DDC interfaces. The SPI interface can be enabled by connecting **D_SEL** to ground. For speed and clock frequency, see the NEO / LEA-M8T Data sheet [2].

1.4.5 TX_READY


The **TX_READY** function is used to indicate when the receiver has data to transmit. A listener can wait on the **TX_READY** signal instead of polling the DDC or SPI interfaces. The UBX-CFG-PRT message lets you configure the polarity and the number of bytes in the buffer before the **TX_READY** signal goes active. The **TX_READY** function can be mapped to **TXD** (PIO 06). The **TX_READY** function is disabled by default.

 The **TX_READY** functionality can be enabled and configured by AT commands sent to the u-blox cellular module supporting the feature. For more information, see the GPS Implementation and Aiding Features in u-blox Wireless Modules [7].

1.5 I/O pins

1.5.1 RESET_N: Reset

Driving **RESET_N** low activates a hardware reset of the system. Use this pin only to reset the module. Do not use **RESET_N** to turn the module on and off, since the reset state increases power consumption. With LEA-M8S and LEA-M8T module **RESET_N** is an input only.

 The RTC time is also reset (but not BBR).

1.5.2 EXTINT: External interrupt

EXTINT0 and **EXTINT1** are external interrupt pins with fixed input voltage thresholds with respect to **VCC** (see the LEA-M8S Data sheet [1] and the NEO / LEA-M8T Data sheet [2] for more information). They can be used for wake-up functions in power save mode and for aiding. Leave open if unused.

The **EXTINT0** pin can also be configured as a generic PIO (PIO13).

The **EXTINT1** pin can also be configured as an active antenna open circuit detection function (**ANT_DET_N**). For further information see sections 1.5.5 and 2.4.4.

Power control

The power control feature allows overriding the automatic active/inactive cycle of power save mode. The state of the receiver can be controlled through the **EXTINT0** and **EXTINT1** pin. The receiver can also be forced OFF using **EXTINT0** and **EXTINT1** when power save mode is not active.

Frequency aiding

The **EXTINT0** and **EXTINT1** pins can be used to supply time or frequency aiding data to the receiver.

For time aiding, hardware time synchronization can be achieved by connecting an accurate time pulse to the **EXTINT0** pin.

Frequency aiding can be implemented by connecting a periodic rectangular signal with a frequency up to 500 kHz and arbitrary duty cycle (low/high phase duration must not be shorter than 50 ns) to the **EXTINT0** pin. Provide the applied frequency value to the receiver using UBX messages.

1.5.3 SAFEBOOT_N

The **SAFEBOOT_N** pin is for future service, updates and reconfiguration.

 Do not pull low during reset.

1.5.4 D_SEL: Interface select (LEA-M8T only)

The **D_SEL** pin selects the available interfaces. SPI cannot be used simultaneously with UART/DDC.

If open, UART and DDC are available. If pulled low, the SPI interface is available. See the NEO / LEA-M8T Data sheet [2].


1.5.5 Antenna open circuit detection (ANT_DET_N)

ANT_DET_N on **EXTINT1** PIO14 is an input pin used to report whether an external circuit has detected an external antenna or not.

- "low" = Antenna detected (antenna consumes current)
- "high" = Antenna not detected (no current drawn). This functionality is by default disabled.

For more information, see section 2.4.4.

Antenna supervision is configurable using message UBX-CFG-ANT.

 Refer to the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification **Error! Reference source not found.** for information about further settings.

1.5.6 TIMEPULSE

A configurable time pulse signal is available on LEA-M8S and LEA-M8T. By default, the time pulse signal is configured to one pulse per second. For more information, see the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3].

1.5.7 TIMEPULSE 2 (LEA-M8T only)

A configurable TIMEPULSE2 signal is available on LEA-M8T module only. For more information see the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3].

1.6 Electromagnetic interference on I/O lines

Any I/O signal line with a length greater than approximately 3 mm can act as an antenna and may pick up arbitrary RF signals, transferring them as noise into the GNSS receiver. This specifically applies to unshielded lines, in which the corresponding GND layer is remote or missing entirely, and to lines close to the edges of the printed circuit board.

If, for example, a cellular signal radiates into an unshielded high-impedance line, it is possible to generate noise in the order of volts and not only distort receiver operation but also damage it permanently. On the other hand, noise generated at the I/O pins will emit from unshielded I/O lines. Receiver performance may be degraded if this noise is coupled to the GNSS antenna (see Figure 18).

To avoid interference by improperly shielded lines, it is recommended to use resistors (e.g. $R > 20 \Omega$), ferrite beads (for example, BLM15HD102SN1) or inductors (for example, LQG15HS47NJ02) on the I/O lines in series. Choose these components with care because they will also affect the signal rise times.

Figure 3 shows an example of EMI protection measures on the RX/TX line using a ferrite bead. More information can be found in section 4.3.

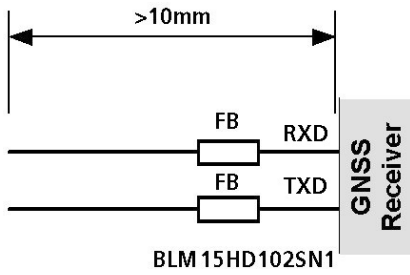


Figure 3: EMI Precautions

2 Design

2.1 Pin description

Function	Pin	No.	I/O	Description	Remarks
Power	VCC	6	I	Supply voltage	Provide clean and stable supply.
	GND	7, 13, 14, 15, 17	-	Ground	Assure a good GND connection to all GND pins of the module.
	VCC_OUT	8	O	Output voltage (VCC)	Leave open if not used.
	V_BCKP	11	I	Backup supply voltage	It is recommended to connect a backup supply voltage to V_BCKP in order to enable warm and hot start features on the positioning modules. Otherwise, connect to VCC.
	VDD_USB	24	I	USB power supply	To use the USB interface connect this pin to 3.0 – 3.6 V. If no USB serial port used connect to GND.
Antenna	RF_IN	16	I	GNSS signal input from antenna	Use a controlled impedance transmission line of 50 Ω to connect to RF_IN.
	VCC_RF	18	O	Output voltage RF section	Can be used to power external LNA or an external active antenna (VCC_RF connected to V_ANT with 10 Ω). The max power consumption of the antenna must not exceed the data sheet specification of the module. Leave open if not used.
	V_ANT	19	I	Antenna bias voltage	Connect to GND (or leave open) if passive antenna is used. If an active antenna is used, add a 10 Ω resistor in front of V_ANT input to the antenna bias voltage or VCC_RF.
	EXTINT1	20	I	Ext. interrupt	Ext. interrupt pin. Int. pull-up resistor to VCC. Can be configured as open circuit detection (ANT_DET_N). Leave open if not used.
UART	TXD (LEA-M8S)	3	O	TXD	Serial port TXD
	TXD / SPI MISO (LEA-M8T)		O	TXD SPI MISO	Serial port TXD if D_SEL = 1 (or open) SPI MISO if D_SEL = 0
	RXD (LEA-M8S)	4	I	RXD	Serial port if RXD
	RXD / SPI MOSI (LEA-M8T)		I	RXD SPI MOSI	Serial port if RXD D_SEL = 1 (or open) SPI MOSI if D_SEL = 0
USB	USB_DM	25	I/O	USB I/O line	USB2.0 bidirectional communication pin. Leave open if unused. For implementations, see section 1.4.
	USB_DP	26	I/O	USB I/O line	
System	RESET_N	10	I	Hardware Reset (Active Low)	Leave open if not used. Do not drive high.
	TIMEPULSE	28	O	Timepulse 1	Configurable timepulse 1 signal (one pulse per second by default). Leave open if not used.
	TP2/SAFEBOOT_N (LEA-M8T)	12	I/O	Safeboot_N / Timepulse 2	Configurable timepulse signal. Must not be held LO during start-up.
	SAFEBOOT_N (LEA-M8S)		I/O	Safeboot_N	Must not be held LO during start-up.
	EXTINT0 / PIO13	27	I / (O)	Ext. interrupt / PIO13	Ext. interrupt pin. Int. pull-up resistor to VCC. Leave open if unused. The pin can also be used as a generic PIO (PIO13).

Function	Pin	No.	I/O	Description	Remarks
	SDA (LEA-M8S)	1	I/O	SDA	DDC data
	SDA / SPI CS_N (LEA-M8T)		I/O	SDA SPI CS_N	DDC data if D_SEL = 1 (or open) SPI chip select if D_SEL = 0
	SCL (LEA-M8S)	2	I/O	SCL	DDC clock
	SCL / SPI CLK (LEA-M8T)		I/O	SCL SPI CLK	DDC clock if D_SEL = 1 (or open) SPI clock if D_SEL = 0
	RESERVED (LEA-M8S)	5	I	Reserved	Leave open
	D_SEL (LEA-M8T)		I	Interface select	D_SEL = 0 -> SPI, D_SEL = 1 (or open) -> DDC
	Reserved	9, 21, 22, 23	-	Reserved	Leave open

Table 2: Pinout LEA-M8S / LEA-M8T

2.1.1 Pin name changes

Selected pin names have been updated to agree with a common naming convention across u-blox modules. The pins have not changed their operation and are the same physical hardware but with updated names. The table below lists the pins that have changed their name along with their old and new names.

No	Previous name	New name
3	TxD (LEA-M8S)	TXD
3	TxD (LEA-M8T)	TXD / SPI MISO
4	RxD (LEA-M8S)	RXD
4	RxD (LEA-M8T)	RXD / SPI MOSI
12	Reserved (LEA-M8S)	SAFEBOOT_N
20	AADET_N	EXTINT1

Table 3: Pin name changes

2.2 Minimal design

This is a minimal setup for a GNSS receiver with a LEA-M8S and LEA-M8T module:

- Passive antenna used
- No backup battery
- UART for communication

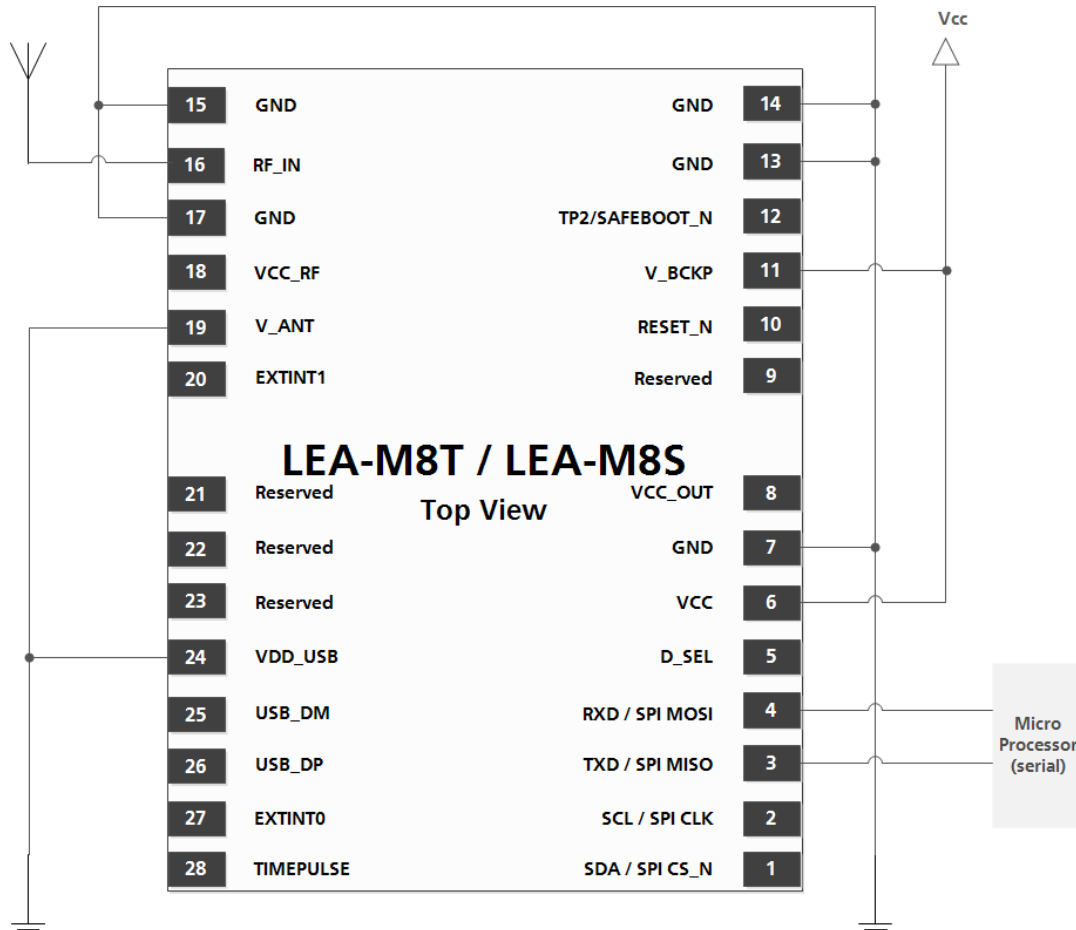


Figure 4: LEA-M8S / LEA-M8T passive antenna design

For active antenna design, see section 2.4.

2.3 Footprint and paste mask

Figure 5 describes the footprint and provides recommendations for the paste mask for the LEA-M8S and LEA-M8T modules. These are recommendations only and not specifications. Note that the copper and solder masks have the same size and position.

To improve the wetting of the half vias, reduce the amount of solder paste under the module and increase the volume outside of the module by defining the dimensions of the paste mask to form a T-shape (or equivalent) extending beyond the copper mask. For the stencil thickness, see Figure 6.

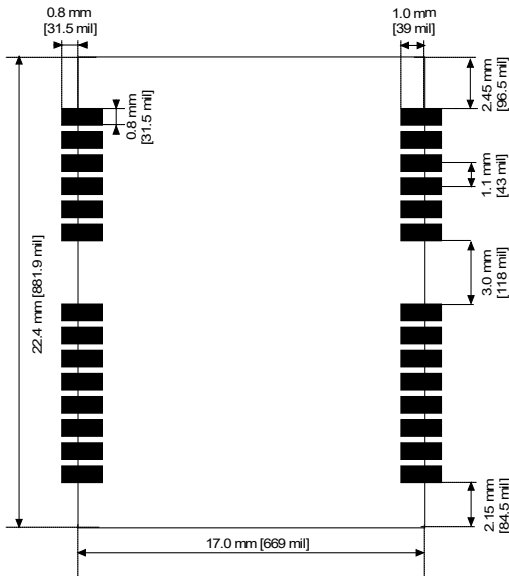


Figure 5: LEA-M8S and LEA-M8T footprint

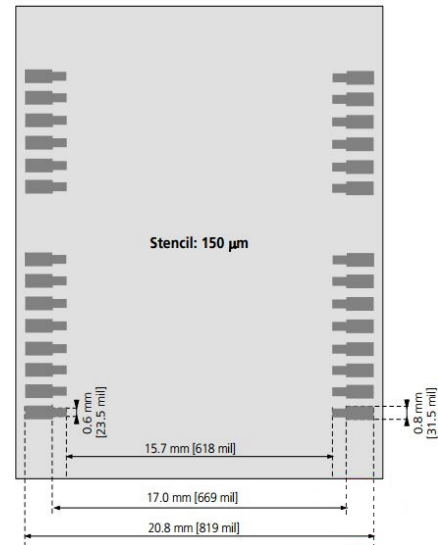


Figure 6: LEA-M8S and LEA-M8T paste mask

2.4 Antenna

For exact pin orientation in any design, see the LEA-M8S Data sheet [1] and the NEO / LEA-M8T Data sheet [2].

For recommended parts, see Appendix B.

2.4.1 Antenna design with passive antenna

A design using a passive antenna requires more attention to the layout of the RF section. Typically, a passive antenna is located near electronic components; therefore, take care to reduce electrical noise that may interfere with the antenna performance. Passive antennas do not require a DC bias voltage and can be directly connected to the RF input pin **RF_IN**. Sometimes they may also need a passive matching network to match the impedance to 50 Ω .

Use an antenna that has sufficient bandwidth to receive all GNSS constellations. For recommended parts, see Appendix B.

Minimal setup with a good patch antenna

Figure 7 shows a minimal setup for a design with a good GNSS patch antenna.

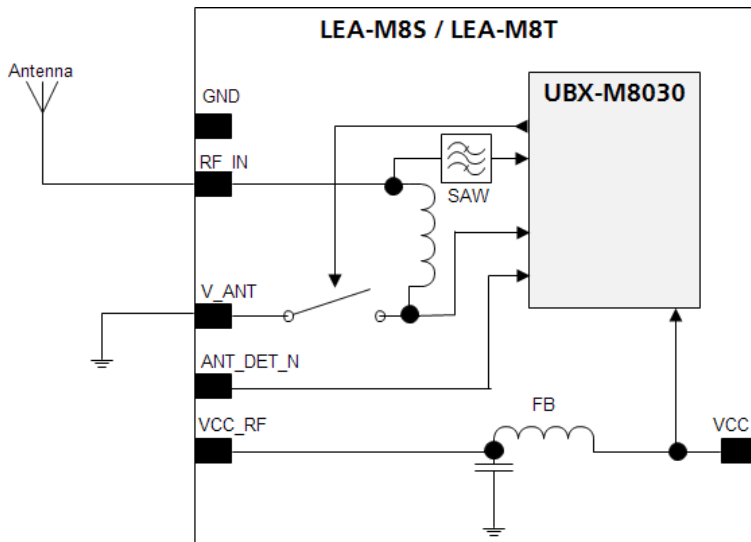


Figure 7: Module design with passive antenna

Setup for best performance with passive antenna

Figure 8 shows a design using an external LNA to increase the sensitivity for best performance with passive antenna.

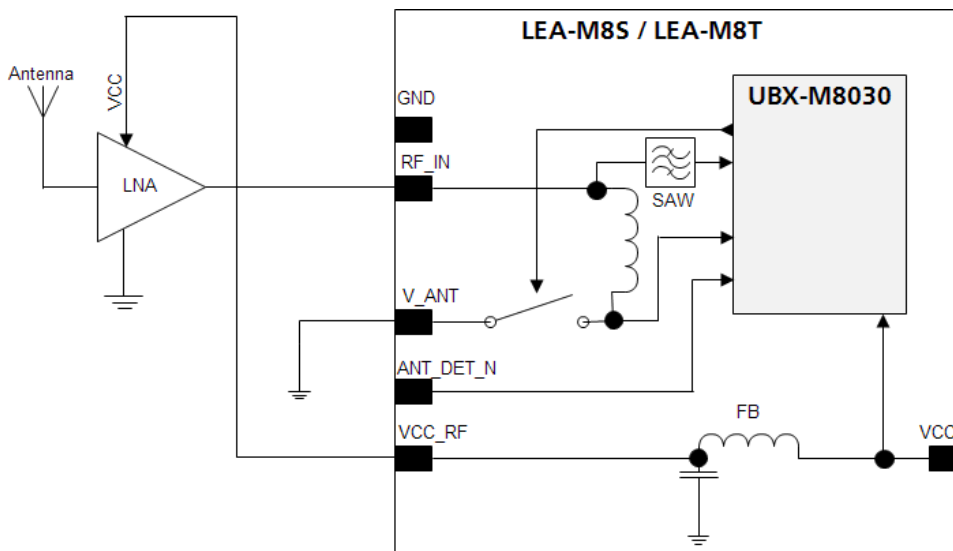


Figure 8: Module design with passive antenna and an external LNA

The **VCC_RF** output can be used to supply the LNA with a filtered supply voltage.

A standard GNSS LNA has enough bandwidth to amplify GPS / Galileo / GLONASS and BeiDou signals.

2.4.2 Active antenna design

Active antennas have an integrated low-noise amplifier. Active antennas require a power supply that will contribute to the total GNSS system power consumption budget with additional 5 to 20 mA typically.

If the customers do not want to make use of the internal antenna supervisor and the supply voltage of the LEA-M8S and LEA-M8T module matches the supply voltage of the antenna (for example, 3.0

V), they can use the filtered supply voltage **VCC_RF** output to supply the antenna (see Figure 9). This design is used for modules in combination with active antenna.

In case of different supply voltage, use a filtered external supply, see Figure 10.

Active antenna design using VCC_RF pin to supply the active antenna

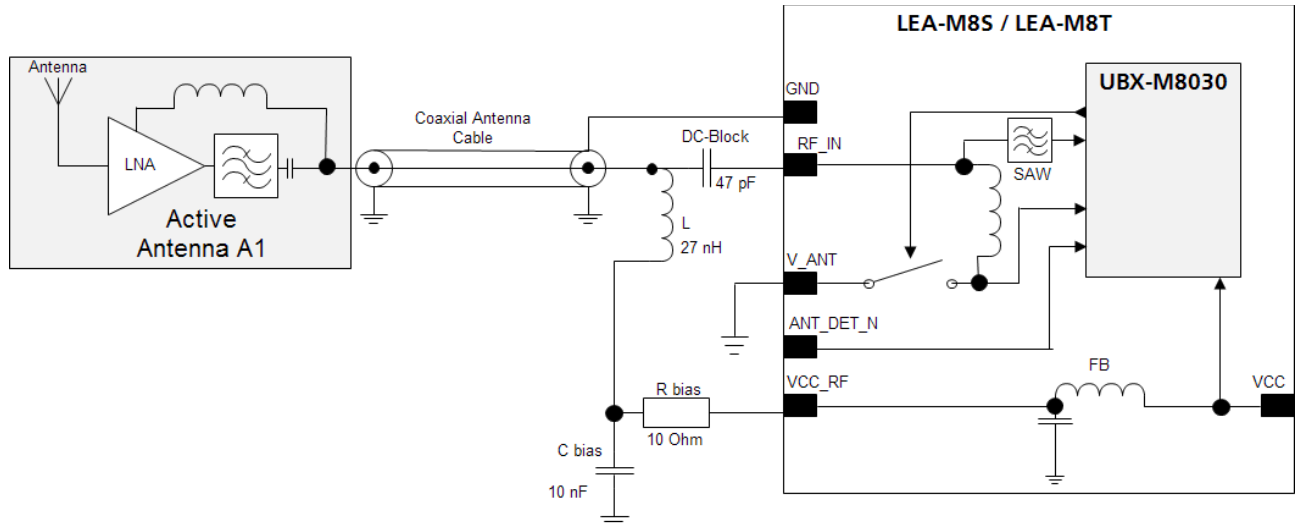


Figure 9: Active antenna design, external supply from VCC_RF

Active antenna design powered from external supply

Figure 10 shows a design with a direct externally powered active antenna.

This circuit has to be used if the active antenna has a different supply voltage than the VCC_RF (for example, if a 5 V active antenna is used).

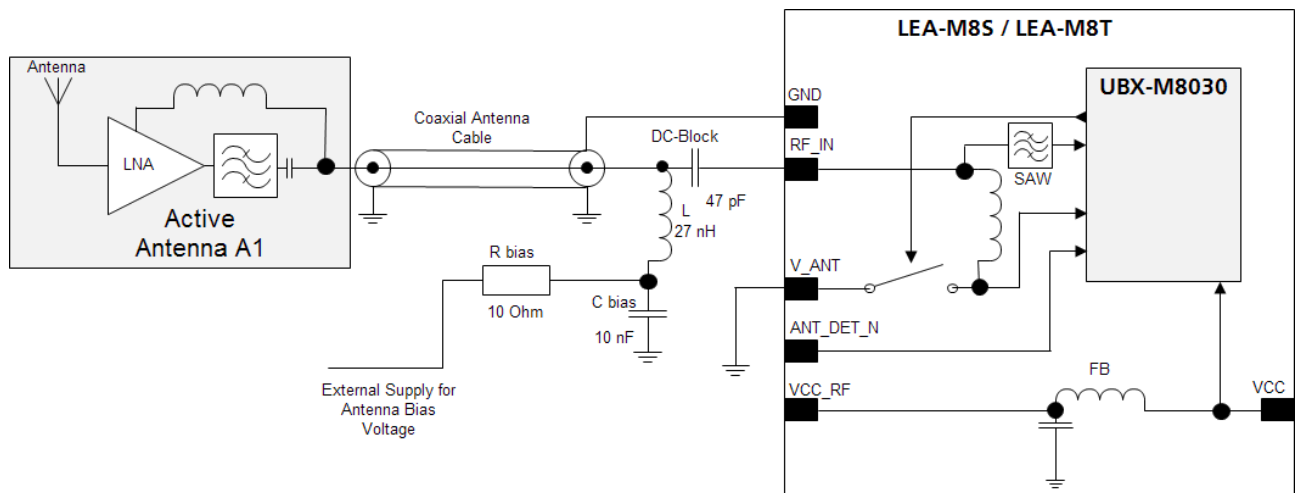


Figure 10: Active antenna design, direct external supply

In case **VCC_RF** voltage does not match with the antenna supply voltage, use a filtered external supply as shown in Figure 10.

Antenna design with active antenna using antenna supervisor

An active antenna supervisor provides the means to check the antenna for open and short circuits and to shut off the antenna supply if a short circuit is detected. The antenna supervisor is configured using serial port UBX binary protocol message. Once enabled, the active antenna supervisor produces status messages, reporting in NMEA and/or UBX binary protocol.

The current active antenna status can be determined by polling the UBX-MON-HW monitor command. If an antenna is connected, the initial state after power-up is “Active Antenna OK.”

The module firmware supports an active antenna supervisor circuit, which is connected to the **ANT_DET_N** pin. For an example of an open circuit detection circuit, see Figure 13.


- "high" = Antenna detected (antenna consumes current)
- "low" = Antenna not detected (no current drawn)

Status reporting

At startup, and on every change of the antenna supervisor configuration, the LEA-M8S module will output an NMEA (**\$GPTXT**) or UBX (**INF-NOTICE**) message with the internal status of the antenna supervisor (disabled, short detection only, enabled).

Abbreviation	Description
AC	Active antenna control enabled
SD	Short circuit detection Enabled
OD	Open circuit detection enabled
PDoS	Short circuit power down logic enabled
SR	Automatic recovery from short state

Table 4: Active antenna supervisor message on startup (UBX binary protocol)

 To activate the antenna supervisor, use the UBX-CFG-ANT message. For further information, refer to the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3].


Similar to the antenna supervisor configuration, the status of the antenna supervisor will be reported in an NMEA (**\$GPTXT**) or UBX (**INF-NOTICE**) message at start-up and on every change.


2.4.3 Power and short detection antenna supervisor

If a suitably dimensioned R_BIAS series resistor is placed in front of the **V_ANT** pin, a short circuit can be detected in the antenna supply. The detection happens inside the u-blox M8 module, after which the antenna supply voltage will be immediately shut down. Afterwards, periodic attempts to re-establish antenna power are made by default.

An internal switch (under control of the receiver) can turn off the supply to the external antenna whenever it is not needed. This feature helps to reduce power consumption in power save mode.

 To configure the antenna supervisor, use the UBX-CFG-ANT message. For further information, see the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3].

 Short circuits on the antenna input without limitation (R_BIAS) of the current can result in permanent damage to the receiver! Therefore, it is mandatory to implement an R_BIAS in all risk applications, such as in situations where the antenna can be disconnected by the end-user or the antenna cables are long.

 In case **VCC_RF** voltage does not match with the antenna supply voltage, use a filtered external supply as shown in Figure 12.

Supply from VCC_RF

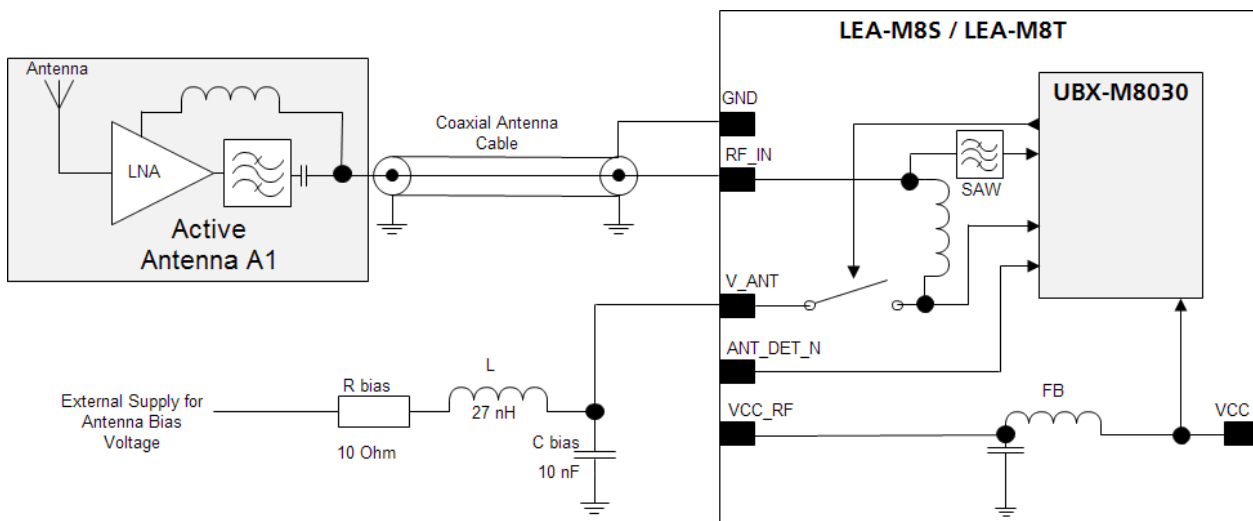
Figure 11 shows an active antenna supplied from the LEA-M8S / LEA-M8T module.

LEA-M8S module includes a built in antenna bias supply for nominal 3 V antennas enabled by linking the filtered **VCC_RF** supply output pin to the **V_ANT** antenna supply input pin with a 10 Ohm resistor in series. The module then controls the power supply to the antenna, applying power whenever the receiver is active and removing power during power-save idle times and if a short-circuit is detected.

The diagram illustrates the connection between the **Active Antenna A1** and the **LEA-M8S / LEA-M8T** module. The antenna section includes an **Antenna**, an **LNA** (Low Noise Amplifier), and a matching network. The signal is transmitted via a **Coaxial Antenna Cable** to the **RF_IN** pin of the **UBX-M8030** module. The module's **GND** is connected to the common ground. The **V_ANT** pin is connected to a **10 Ohm** resistor (**R bias**) and a **10 nF** capacitor (**C bias**) to ground. The **ANT_DET_N** pin is connected to the module's internal circuitry. The **VCC_RF** pin is connected to the **VCC** supply through a **FB** (ferrite bead) and a **10 nF** capacitor to ground. The **UBX-M8030** module also includes a **SAW** (Surface Acoustic Wave) filter and a **SW** (switch) component.

External supply

Since the external bias voltage is fed into the most sensitive part of the receiver (the RF input), this supply should be free of noise. Usually, low frequency analog noise is less critical than digital noise of spurious frequencies with harmonics up to the GPS/QZSS band of 1.575 GHz, GLONASS band of 1.602 GHz and BeiDou band at 1.561 GHz. Therefore, it is not recommended to use digital supply nets to feed the **V_ANT** pin.



2.4.4 Power, short and open detection antenna supervisor

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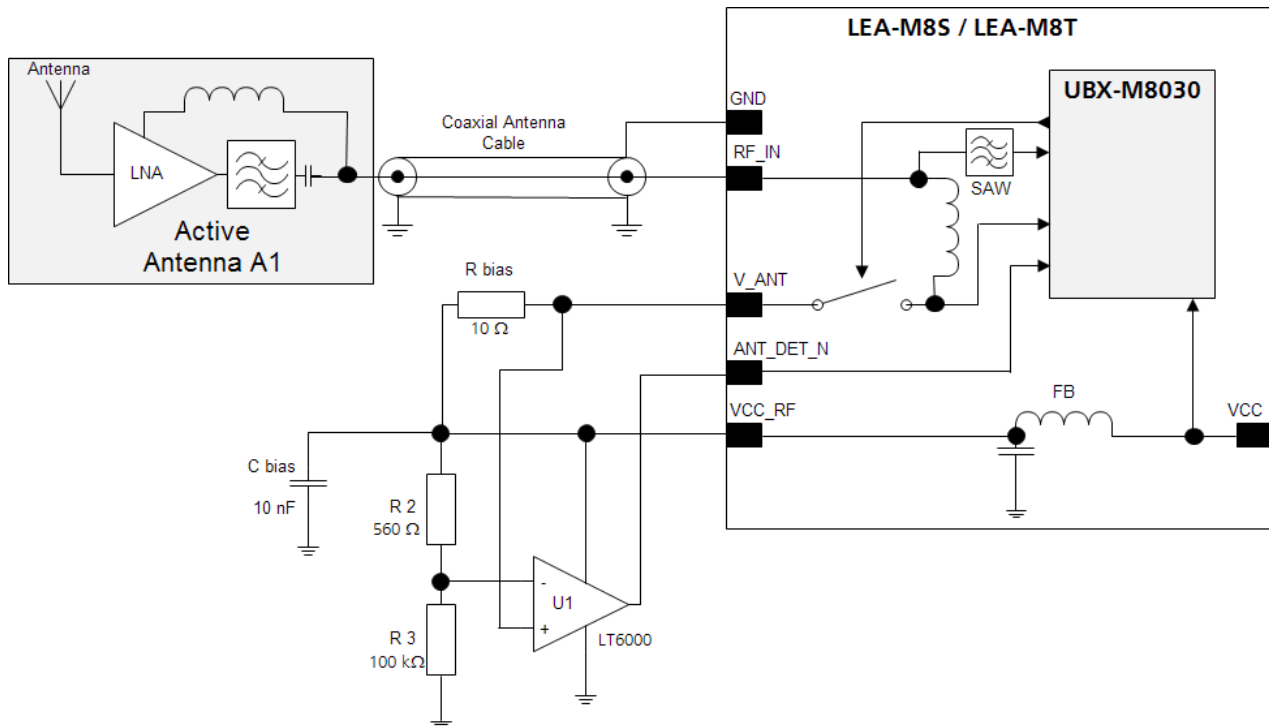


Figure 13: Schematic of open circuit detection

$$I = \left(\frac{R2}{R2 + R3} \right) \cdot Vcc_RF$$

Equation 1: Calculation of threshold current for open circuit detection

If the antenna supply voltage is not derived from **VCC_RF**, do not exceed the maximum voltage rating of **ANT_DET_N**.

2.5 Layout design-in: Thermal management


During design-in do not place the module near sources of heating or cooling. The receiver oscillator is sensitive to sudden changes in ambient temperature which can adversely impact satellite signal tracking. Sources can include co-located power devices, cooling fans or thermal conduction via the PCB. Take into account the following questions when designing in the module.

- Is the receiver placed away from heat sources?
- Is the receiver placed away from air-cooling sources?
- Is the receiver shielded by a cover/case to prevent the effects of air currents and rapid environmental temperature changes?

3 Migration to u-blox M8 modules

3.1 Migrating u-blox 6 designs to u-blox M8 module

u-blox is committed to ensuring that products in the same form factor are backwards compatible over several technology generations. The utmost care has been taken to ensure there is no negative impact on function or performance and to make u-blox M8 modules as fully compatible with previous generation modules as possible. If using BeiDou, check the bandwidth of the external RF components and the antenna. For information about power consumption, see the LEA-M8S Data sheet [1] and the NEO / LEA-M8T Data sheet [2]. It is highly advisable that customers consider a design review with the u-blox support team to ensure the compatibility of key functionalities.

 Selected pin names have been updated to agree with a common naming convention across u-blox modules. The pins have not changed their operation and are the same physical hardware but with updated names.

3.2 Hardware migration LEA-6N -> LEA-M8S

Pin	LEA-6N		LEA-M8S		Remarks for migration
	Pin name	Typical assignment	Pin name	Typical assignment	
1	SDA	DDC data	SDA	DDC data	No difference
2	SCL	DDC clock	SCL	DDC clock	No difference
3	TxD	Serial port	TXD	Serial port	No difference
4	RxD	Serial port	RXD	Serial port	No difference
5	NC	Not connected	Reserved	Not connected	No difference
6	VCC	Supply voltage	VCC	Supply voltage	No difference
7	GND	Ground (digital)	GND	Ground (digital)	No difference
8	VCC_OUT	Output voltage	VCC_OUT	Output voltage	No difference
9	NC	Not connected	Reserved	Not connected	No difference
10	RESET_N	External reset	RESET_N	External reset	No difference
11	V_BCKP	Backup voltage supply	V_BCKP	Backup voltage supply	If this was connected to GND on u-blox 6 module, OK to do the same in M8.
12	Reserved	SAFEBOOT_N, Do not drive low	SAFEBOOT_N	Do not drive low	No difference
13	GND	Ground	GND	Ground	No difference
14	GND	Ground	GND	Ground	No difference
15	GND	Ground	GND	Ground	No difference
16	RF_IN	GNSS signal input	RF_IN	GNSS signal input	No difference
17	GND	Ground	GND	Ground	No difference
18	VCC_RF	Output voltage RF section	VCC_RF	Output voltage RF section	No difference
19	V_ANT	Antenna bias voltage	V_ANT	Antenna bias voltage	No difference
20	AADET_N	Active antenna detect	EXTINT1	Active antenna detect	No difference
21	Reserved	Not connected	Reserved	Not connected	No difference
22	Reserved	Not connected	Reserved	Not connected	No difference
23	Reserved	Not connected	Reserved	Not connected	No difference
24	VDD_USB	USB supply	VDD_USB	USB supply	No difference
25	USB_DM	USB data	USB_DM	USB data	No difference
26	USB_DP	USB data	USB_DP	USB data	No difference

27	EXTINT0	External interrupt pin	EXTINT0	External interrupt pin	No difference
28	TIMEPULSE	Timepulse (1PPS)	TIMEPULSE	Time pulse 1	No difference


Table 5: Pin-out comparison LEA-6N vs. LEA-M8S

3.3 Hardware migration LEA-6T -> LEA-M8T

Pin	LEA-6T		LEA-M8T		Remarks for migration
	Pin name	Typical assignment	Pin name	Typical assignment	
1	SDA	DDC data	SDA / SPI CS_N	DDC data	No difference
2	SCL	DDC clock	SCL / SPI CLK	DDC clock	No difference
3	TxD	Serial port	TXD / SPI MISO	Serial port	No difference
4	RxD	Serial port	RXD / SPI MOSI	Serial port	No difference
5	NC	Not connected	D_SEL	D_SEL = 1 (or open)	Do not drive low
6	VCC	Supply voltage	VCC	Supply voltage	No difference
7	GND	Ground (digital)	GND	Ground (digital)	No difference
8	VCC_OUT	Output voltage	VCC_OUT	Output voltage	No difference
9	TIMEPULSE2	2 nd Time pulse	Not Connected	Reserved	Time pulse 2 is now available on pin 12 (TP2/SAFEBOOT_N)
10	RESET_N	External reset	RESET_N	External reset	No difference
11	V_BCKP	Backup voltage supply	V_BCKP	Backup voltage supply	If this was connected to GND on u-blox 6 module, OK to do the same in M8.
12	Reserved	Safeboot_N	TP2/SAFEBOOT_N	Safeboot_N / Time pulse 2	Must not be held LO during start-up.
13	GND	Ground	GND	Ground	No difference
14	GND	Ground	GND	Ground	No difference
15	GND	Ground	GND	Ground	No difference
16	RF_IN	GNSS signal input	RF_IN	GNSS signal input	No difference
17	GND	Ground	GND	Ground	No difference
18	VCC_RF	Output voltage RF section	VCC_RF	Output voltage RF section	No difference
19	V_ANT	Antenna bias voltage	V_ANT	Antenna bias voltage	No difference
20	AADET_N	Active antenna detect	EXTINT1	External interrupt pin/ Active antenna detect	
21	Reserved	Not connected	Reserved	Not connected	No difference
22	Reserved	Not connected	Reserved	Not connected	No difference
23	Reserved	Not connected	Reserved	Not connected	No difference
24	VDD_USB	USB supply	VDD_USB	USB supply	No difference
25	USB_DM	USB data	USB_DM	USB data	No difference
26	USB_DP	USB data	USB_DP	USB data	No difference
27	EXTINT0	External interrupt pin	EXTINT0	External interrupt pin	No difference
28	TIMEPULSE1	Time pulse (1PPS)	TIMEPULSE1	Time pulse (1PPS)	No difference

Table 6: Pin-out comparison LEA-6T vs. LEA-M8T

3.4 Software migration


 For overall description of the module software operation, see the u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification [3]. For migration, see the u-blox M8 FW SPG3.01 Migration Guide [8].

4 Product handling

4.1 Packaging, shipping, storage and moisture preconditioning

For information pertaining to reels and tapes, moisture sensitivity levels (MSL), shipment and storage information, as well as drying for preconditioning see the LEA-M8S Data sheet [1] and NEO / LEA-M8T Data sheet [2].

Population of modules

-  When populating the modules, make sure that the pick and place machine is aligned to the copper pins of the module and not on the module edge.

4.2 Soldering


Soldering paste

Use of “No Clean” soldering paste is strongly recommended, as it does not require cleaning after the soldering process has taken place. The paste given in the example below meets these criteria.

- Soldering paste: OM338 SAC405 / Nr.143714 (Cookson Electronics)
- Alloy specification: Sn 95.5/ Ag 4/ Cu 0.5 (95.5% tin/ 4% silver/ 0.5% copper)
- Melting temperature: 217 °C
- Stencil thickness: See Figure 6.

The final choice of the soldering paste depends on the approved manufacturing procedures.

The paste-mask geometry for applying soldering paste must meet the recommendations.

-  The quality of the solder joints on the connectors ('half vias') must meet the appropriate IPC specification.

Reflow soldering

A convection-type soldering oven is highly recommended over the infrared-type radiation oven. Convection-heated ovens allow precise control of the temperature, and all parts will heat up evenly, regardless of material properties, thickness of components and surface color.

As a reference, see the IPC-7530 Guidelines for temperature profiling for mass soldering (reflow and wave) processes, published in 2001.

Preheat phase

During the initial heating of component leads and balls, residual humidity will be dried out. Note that this preheat phase will not replace prior baking procedures.

- Temperature rise rate: max 3 °C/s. If the temperature rise is too rapid in the preheat phase it may cause excessive slumping.
- Time: 60 – 120 s. If the preheat is insufficient, rather large solder balls tend to generate. Conversely, if performed excessively, fine balls and large balls will generate in clusters.
- End temperature: 150 – 200 °C. If the temperature is too low, non-melting tends to be caused in areas containing large heat capacity.

Heating/ Reflow phase


The temperature rises above the liquidus temperature of 217 °C. Avoid a sudden rise in temperature as the slump of the paste could become worse.

- Limit time above 217 °C liquidus temperature: 40 – 60 s
- Peak reflow temperature: 245 °C

Cooling phase

A controlled cooling avoids negative metallurgical effects of the solder (the solder becomes more brittle) and possible mechanical tensions in the products. Controlled cooling helps to achieve bright solder fillets with good shape and low contact angle.

- Temperature fall rate: max 4 °C/s

 To avoid falling off, place the u-blox M8 GNSS module on the topside of the motherboard during soldering.

The final soldering temperature chosen at the factory depends on additional external factors such as choice of soldering paste, size, thickness and properties of the baseboard. Exceeding the maximum soldering temperature in the recommended soldering profile may permanently damage the module.

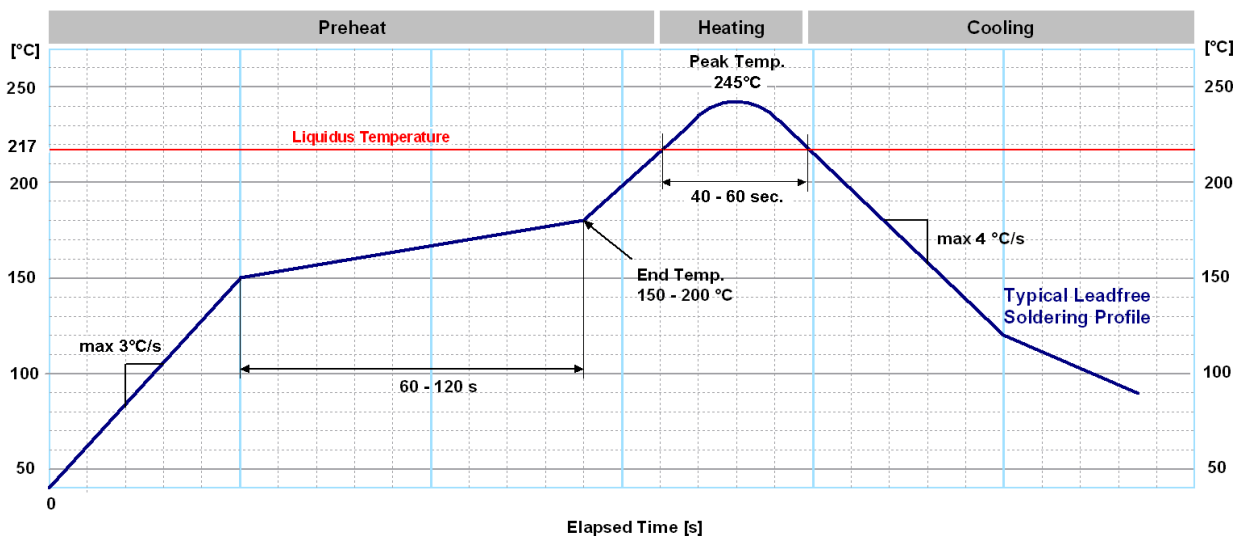



Figure 14: Recommended soldering profile

 u-blox M8 modules **must not** be soldered with a damp heat process.

Optical inspection

After soldering the u-blox M8 module, consider an optical inspection step to check whether:

- The module is properly aligned and centered over the pads.
- All pads are properly soldered.
- No excess solder has created contacts to neighboring pads, or possibly to pad stacks and vias nearby.

Cleaning

In general, cleaning the populated modules is strongly discouraged. Residues underneath the modules cannot be easily removed with a washing process.


- Cleaning with water will lead to capillary effects where water is absorbed into the gap between the baseboard and the module. The combination of residues of soldering flux and encapsulated water leads to short circuits or resistor-like interconnections between neighboring pads.
- Cleaning with alcohol or other organic solvents can result in soldering flux residues flooding into the two housings, areas that are not accessible for post-wash inspections. The solvent will also damage the sticker and the ink-jet printed text.
- Ultrasonic cleaning will permanently damage the module, in particular the quartz oscillators.

The best approach is to use a “no clean” soldering paste and eliminate the cleaning step after the soldering.

Repeated reflow soldering

Only single reflow soldering processes are recommended for boards populated with u-blox M8 modules. To avoid upside down orientation during the second reflow cycle, the M8 modules should not be submitted to two reflow cycles on a board populated with components on both sides. In such a case, the module should always be placed on that side of the board which is submitted into the last reflow cycle. This is because of the risk of the module falling off due to the significantly higher weight in relation to other components.

You can consider two reflow cycles by excluding the above described upside down scenario and taking into account the rework conditions described in section 4.

 Repeated reflow soldering processes and soldering the module upside down are not recommended.

Wave soldering


Baseboards with combined through-hole technology (THT) components and surface-mount technology (SMT) devices require wave soldering to solder the THT components. Only a single wave soldering process is encouraged for boards populated with u-blox M8 modules.

Hand soldering


Hand soldering is allowed. Use a soldering iron temperature-setting equivalent to 350 °C. Place the module precisely on the pads. Start with a cross-diagonal fixture soldering (for example, pins 1 and 15), and continue from left to right.

Rework

The u-blox M8 module can be unsoldered from the baseboard using a hot air gun. When using a hot air gun for unsoldering the module, a maximum of one reflow cycle is allowed. Using a hot air gun is not recommended because it is an uncontrolled process and might damage the module.

 Attention: use of a hot air gun can lead to overheating and severely damage the module. Always avoid overheating the module.


After the module is removed, clean the pads before placing and hand soldering a new module.

 Never attempt a rework on the module itself, for example, by replacing individual components. Such actions immediately terminate the warranty.

In addition to the two reflow cycles, manual rework on particular pins by using a soldering iron is allowed. Manual rework steps on the module can be done several times.


Conformal coating

Certain applications employ a conformal coating of the PCB using HumiSeal® or other related coating products. These materials affect the HF properties of the GNSS module and it is important to prevent them from flowing into the module. The RF shields do not provide 100% protection for the module from coating liquids with low viscosity; therefore, take care when applying the coating.

 Conformal coating of the module will void the warranty.


Casting

If casting is required, use viscose or another type of silicon pottant. The OEM is strongly advised to qualify such processes in combination with the u-blox M8 module before implementing it in the production.

 Casting will void the warranty.


Grounding metal covers

Attempts to improve grounding by soldering ground cables, wick or other forms of metal strips directly onto the EMI covers is done at the customer's own risk. The numerous ground pins should be sufficient to provide optimum immunity to interferences and noise.

-  u-blox offers no warranty against damages to the u-blox M8 module caused by soldering metal cables or any other forms of metal strips directly onto the EMI covers.



Use of ultrasonic processes

Some components on the u-blox M8 module are sensitive to ultrasonic waves. Use of any ultrasonic processes (cleaning, welding, and so on) may cause damage to the GNSS receiver.

-  u-blox offers no warranty against damages to the u-blox M8 module caused by any ultrasonic processes.

4.3 EOS/ESD/EMI precautions

When integrating GNSS positioning modules into wireless systems, consider the electromagnetic and voltage susceptibility issues carefully. Wireless systems include components that can produce electrical overstress (EOS) and electro-magnetic interference (EMI). CMOS devices are more sensitive to such influences because their failure mechanism is defined by the applied voltage, whereas bipolar semiconductors are more susceptible to thermal overstress. The following design guidelines help you in designing robust yet cost effective solutions.

-  To avoid overstress damage during production or in the field, it is essential to observe strict EOS/ESD/EMI handling and protection measures.
-  To prevent overstress damage at the RF_IN of your receiver, never exceed the maximum input power (see the LEA-M8S Data sheet [1] and the NEO-M8T / LEA-M8T Data sheet [2]).

Electrostatic discharge (ESD)

Electrostatic discharge (ESD) is the sudden and momentary electric current that flows between two objects at different electrical potentials caused by direct contact or induced by an electrostatic field. The term is usually used in the electronics and other industries to describe momentary unwanted currents that may cause damage to electronic equipment.



ESD handling precautions

ESD prevention is based on establishing an electrostatic protective area (EPA). The EPA can be a small working station or a large manufacturing area. The main principle of the EPA is that there are no highly charging materials near ESD-sensitive electronics, all conductive materials and workers are grounded, and charge build-up on ESD-sensitive electronics is prevented. International standards are used to define typical EPA and can be obtained for example from International Electrotechnical Commission (IEC) or American National Standards Institute (ANSI).

GNSS positioning modules are sensitive to ESD and require special precautions when handling. Particular care must be exercised when handling patch antennas, due to the risk of electrostatic charges. In addition to standard ESD safety practices, take the following measures into account whenever handling the receiver.

- Unless there is a galvanic coupling between the local GND (the work table) and the PCB GND, the first point of contact when handling the PCB must always be between the local GND and PCB GND.
- Before mounting an antenna patch, connect ground of the device.
- When handling the RF pin, do not come into contact with any charged capacitors and be careful when contacting materials that can develop charges (such as patch antenna ~10 pF, coax cable ~50 – 80 pF/m, soldering iron).
- To prevent electrostatic discharge through the RF input, do not touch any exposed antenna area. If there is any risk that such exposed antenna area is touched in a non-ESD protected work area, implement proper ESD protection measures in the design.
- When soldering RF connectors and patch antennas to the receiver's RF pin, make sure to use an ESD-safe soldering iron (tip).



⚠ Failure to observe these precautions can result in severe damage to the GNSS module!

ESD protection measures

- ⚠** GNSS positioning modules are sensitive to electrostatic discharge (ESD). Special precautions are required when handling.
- 🔧** For more robust designs, employ additional ESD protection measures. Using an LNA with the appropriate ESD rating can provide enhanced GNSS performance with passive antennas and increases ESD protection.

Most defects caused by ESD can be prevented by following strict ESD protection rules for production and handling. When implementing passive antenna patches or external antenna connection points, additional ESD measures can also avoid failures in the field as shown in Figure 15.

Small passive antennas (<2 dBic and performance critical)	Passive antennas (>2 dBic or performance sufficient)	Active antennas
<p>A</p> <p>LNA with appropriate ESD rating</p>	<p>B</p>	<p>C</p>

Figure 15: ESD precautions

- 🔧** Protection measure A is preferred because it offers the best GNSS performance and the best level of ESD protection.

Electrical overstress (EOS)

Electrical overstress (EOS) usually describes situations where the maximum input power exceeds the maximum specified ratings. EOS failure can happen if RF emitters are close to a GNSS receiver or its

antenna. EOS causes damage to the chip structures. If the RF_IN is damaged by EOS, it is hard to determine whether the chip structures have been damaged by ESD or EOS.

EOS protection measures

- For designs with GNSS positioning modules and wireless (for example, GSM/GPRS) transceivers in close proximity, ensure sufficient isolation between the wireless and GNSS antennas. If wireless power output causes the specified maximum power input at the GNSS RF_IN to exceed, employ EOS protection measures to prevent overstress damage.

For robustness, EOS protection measures as shown in Figure 16 are recommended for designs combining wireless communication transceivers (for example, GSM, GPRS) and GNSS in the same design or in close proximity.

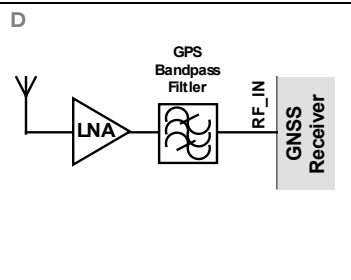
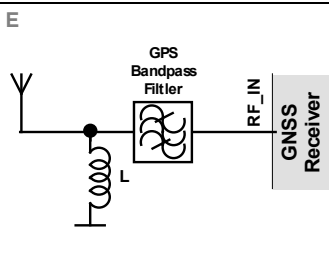
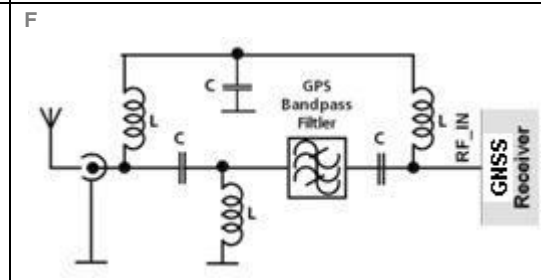
Small passive antennas (<2 dBic and performance critical)	Passive antennas (>2 dBic or performance sufficient)	Active antennas (without internal filter which needs the module antenna supervisor circuits)
		
LNA with appropriate ESD rating and maximum input power	GNSS band pass Filter: SAW or ceramic with low insertion loss and appropriate ESD rating	

Figure 16: EOS and ESD precautions

Electromagnetic interference (EMI)

Electromagnetic interference (EMI) is the addition or coupling of energy causing a spontaneous reset of the GNSS receiver or resulting in unstable performance. In addition to EMI degradation due to self-jamming (see section 1.5), any electronic device near the GNSS receiver can emit noise that can lead to EMI disturbances or damage.

The following elements are critical regarding EMI:

- Unshielded connectors (for example, pin rows)
- Weakly shielded lines on PCB (for example, on the top or the bottom layer and especially at the border of a PCB)
- Weak GND concept (for example, small and/or long ground line connections)

EMI protection measures are recommended when RF-emitting devices are near the GNSS receiver. To minimize the effect of EMI, a robust grounding concept is essential. To achieve electromagnetic robustness, follow the standard EMI suppression techniques:

<http://www.murata.com/products/emc/knowhow/index.html>

<http://www.murata.com/products/emc/knowhow/pdf/4to5e.pdf>

Improved EMI protection can be achieved by inserting a resistor or, better yet, a ferrite bead or an inductor (see Table 8: Recommended parts

) into any unshielded PCB lines connected to the GNSS receiver. Place the resistor as close to the GNSS receiver pin as possible.

Alternatively, feed-through capacitors with good GND connection can be used to protect, for example, the **VCC** supply pin against EMI. A selection of feed-through capacitors is listed in Table 8.

Intended use

- To mitigate any performance degradation of a radio equipment under EMC disturbance, system integration shall adopt appropriate EMC design practice and shall not contain cables over three meters on signal and supply ports.

4.4 Applications with cellular modules

GSM terminals transmit power levels up to 2 W (+33 dBm) peak, 3G and LTE up to 250 mW continuous. Consult the LEA-M8S Data sheet [1] and the NEO-M8T / LEA-M8T Data sheet [2] for the absolute maximum power input at the GNSS receiver.

- See GPS Implementation and Aiding Features in u-blox Wireless Modules [7].

Isolation between GNSS and GSM antenna

In a handheld-type design, an isolation of approximately 20 dB can be reached with careful placement of the antennas. If such isolation cannot be achieved, for example, in the case of an integrated cellular /GNSS antenna, an additional input filter is needed on the GNSS side to block the high energy emitted by the GSM transmitter. Examples of these kinds of filters are SAW Filters from Epcos (B9444 or B7839) or Murata.

Increasing interference immunity

Interference signals come from in-band and out-band frequency sources.

In-band interference

With in-band interference, the signal frequency is very close to the GNSS constellation frequency used, for example, GPS frequency of 1575 MHz (see Figure 17). Such interference signals are typically caused by harmonics from displays, micro-controller, bus systems, and so on.

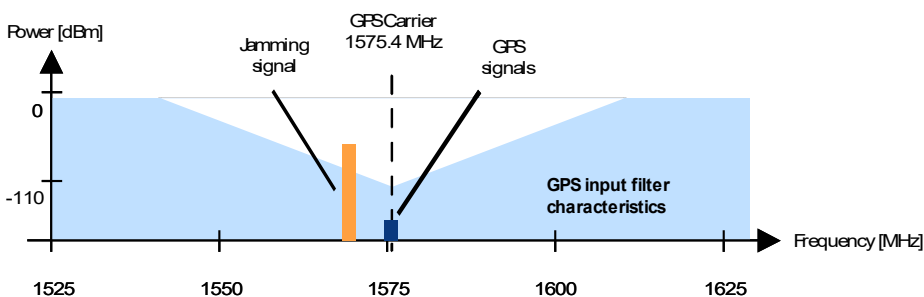


Figure 17: In-band interference signals

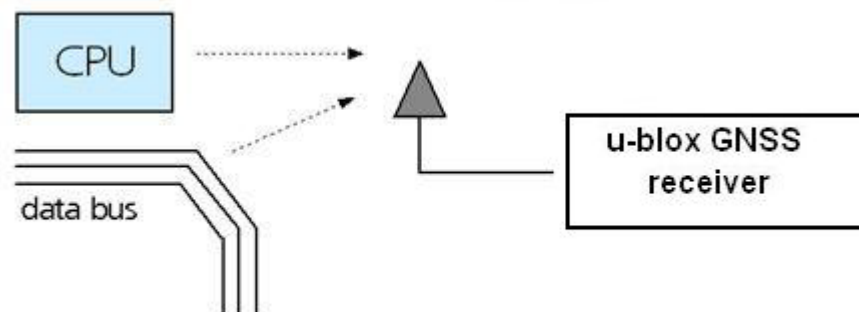


Figure 18: In-band interference sources

Measures against in-band interference include:

- Maintaining a good grounding concept in the design
- Shielding
- Layout optimization
- Filtering
- Placement of the GNSS antenna
- Adding a CDMA, GSM, WCDMA band pass filter before handset antenna

Out-band interference

Out-band interference is caused by signal frequencies that are different from the GNSS carrier (see Figure 19). The main sources are wireless communication systems such as cellular, CDMA, WCDMA, Wi-Fi, BT, and so on.

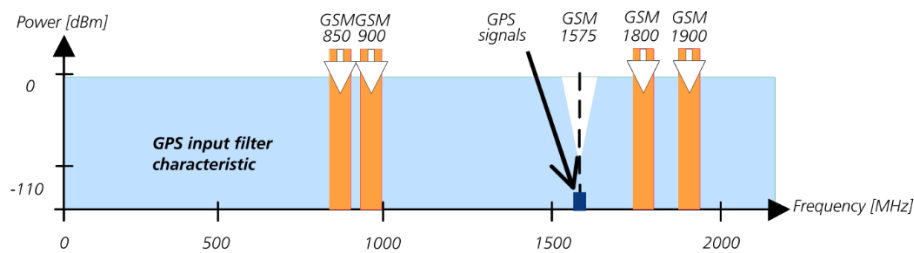


Figure 19: Out-band interference signals

Measures against out-band interference include maintaining a good grounding concept in the design and adding a SAW or band pass ceramic filter (as recommend in section 4) into the antenna input line to the GNSS receiver (see Figure 20).



Figure 20: Measures against in-band interference

Appendix

A Glossary

Abbreviation	Definition
ANSI	American National Standards Institute
BeiDou	Chinese navigation satellite system
CDMA	Code Division Multiple Access
EMC	Electromagnetic compatibility
EMI	Electromagnetic interference
EOS	Electrical Overstress
EPA	Electrostatic Protective Area
ESD	Electrostatic discharge
Galileo	European navigation system
GLONASS	Russian satellite system
GND	Ground
GNSS	Global Navigation Satellite System
GPS	Global Positioning System
GSM	Global System for Mobile Communications
IEC	International Electrotechnical Commission
PCB	Printed circuit board
QZSS	Quasi-Zenith Satellite System

Table 7: Explanation of the abbreviations and terms used

B Recommended parts

Recommended parts are selected on data sheet basis only. Other components may also be used.

	Manufacturer	Part ID	Remarks	Parameters to consider
Diode Semiconductor	ON	ESD9R3.3ST5G	Standoff voltage>3.3 V	Low capacitance < 0.5 pF
		ESD9L3.3ST5G	Standoff voltage>3.3 V	Standoff voltage > Voltage for active antenna
		ESD9L5.0ST5G	Standoff voltage>5 V	Low inductance
SAW	TDK/EPCOS	B8401: B39162-B8401-P810	GPS+GLONASS	High attenuation
	TDK/EPCOS	B3913: B39162B3913U410	GPS+GLONASS+BeiDou	For automotive applications
	TDK/EPCOS	B4310: B39162B4310P810	GPS+GLONASS	Compliant to the AEC-Q200 standard
	ReyConns	NDF9169	GPS+ BeiDou	Low insertion loss, only for mobile applications
	Murata	SAFFB1G56KB0F0A	GPS+GLONASS+BeiDou	Low insertion loss, only for mobile applications
	Murata	SAFEA1G58KB0F00	GPS+GLONASS	Low insertion loss, only for mobile applications
	Murata	SAFEA1G58KA0F00	GPS+GLONASS	High attenuation, only for mobile applications
	Murata	SAFFB1G58KA0F0A	GPS+GLONASS	High attenuation, only for mobile applications
	Murata	SAFFB1G58KB0F0A	GPS+GLONASS	Low insertion loss, only for mobile applications

	Manufacturer	Part ID	Remarks	Parameters to consider
	TAI-SAW	TA1573A	GPS+GLONASS	Low insertion loss
	TAI-SAW	TA1343A	GPS+GLONASS+BeiDou	Low insertion loss
	TAI-SAW	TA0638A	GPS+GLONASS+BeiDou	Low insertion loss
LNA	JRC	NJG1143UA2	LNA	Low noise figure, up to 15 dBm RF input power
Inductor	Murata	LQG15H series, e.g. LQG15HS47NJ02 LQG15HN27NJ02	L, 47 nH down to 27 nH	Impedance at freq. GNSS > 500 Ω
	Murata	LQW15A series, e.g. LQW15AN47NJ80 LQW15AN75NJ80	L, 47 nH up to 75 nH	
	Johansson Technology	L-07W series e.g. 39 nH L-07W39NJV4T	or any other inductance compatible with the above Murata inductors	
Capacitor	Murata	GRM1555C1E470JZ01	C _{DC-block} , 47 pF	DC-block
	Murata	X7R 10N 10% 16 V	C _{Bias} , 10 nF	Bias-T
Ferrite bead	Murata	BLM15HD102SN1	FB	High IZI at fGSM
Feed-through capacitor for signal	Murata	NFL18SP157X1A3	Monolithic type	For data signals, 34 pF load capacitance
		NFA18SL307V1A45	Array type	For data signals, 4 circuits in 1 package
Feed-through capacitor	Murata	NFM18PC NFM21P....	0603 2A 0805 4A	R _s < 0.5 Ω
Resistor		10 $\Omega \pm 10\%$, min 0.250 W	R _{bias}	
		560 $\Omega \pm 5\%$	R2	
		100 k $\Omega \pm 5\%$	R3, R4	

Table 8: Recommended parts

Recommended antennas


Manufacturer	Order no.	Comments
Hirschmann (www.hirschmann-car.com)	GLONASS 9 M	GPS+GLONASS active
Taoglas (www.taoglas.com)	AA.160.301111	36 x 36 x 4 mm, 3-5V 30 mA active
Taoglas (www.taoglas.com)	AA.161.301111	36 x 36 x 3 mm, 1.8 to 5.5 V / 10 mA at 3 V active
INPAQ (http://www.inpaq.com.tw/)	B3G02G-S3-01-A	2.7 to 3.9 V / 10 mA active
Amotech (www.amotech.co.kr)	B35-3556920-2J2	35 x 35 x 3 mm GPS+GLONASS passive
Amotech (www.amotech.co.kr)	A25-4102920-2J3	25 x 25 x 4 mm GPS+GLONASS passive
Amotech (www.amotech.co.kr)	A18-4135920-AMT04	18 x 18 x 4 mm GPS+GLONASS passive
Amotech (www.amotech.co.kr)	Amotech AGA363913-S0-A1	GPS+GLONASS+ BeiDou active
INPAQ (http://www.inpaq.com.tw/)	ACM4-5036-A1-CC-S	5.2 x 3.7 x 0.7 mm GPS+GLONASS passive

Additional antenna Manufacturer: Allis Communications, 2J, Tallysman Wireless

Table 9: Recommend antennas

Related documents

- [1] LEA-M8S (FW3) Data sheet, doc. no. UBX-16010205
- [2] NEO / LEA-M8T (FW3) Data sheet, doc. no. UBX-15025193
- [3] u-blox 8 / u-blox M8 Receiver Description Including Protocol Specification (Public version), doc. no. UBX-13003221
- [4] GPS Antenna application note, doc. no. GPS-X-08014
- [5] GPS Compendium, doc. no. GPS-X-02007
- [6] I2C-bus specification, Rev. 6 - 4 April 2014,
http://www.nxp.com/documents/user_manual/UM10204.pdf
- [7] GPS Implementation and Aiding Features in u-blox Wireless Modules, doc. no. GSM.G1-CS-09007
- [8] u-blox M8 FW SPG3.01 migration guide, doc. no. UBX-15028330

 For regular updates to u-blox documentation and to receive product change notifications, register on our homepage (www.u-blox.com).

Revision history

Revision	Date	Name	Comments
R01	12-Feb-2016	jfur	Objective Specification
R02	15-June-2016	jfur	Advance Information, Pin name updated
R03	08-Aug-2016	jfur	Production Information
R04	26-Sep-2017	msul	Added information on RED DoC in European Union regulatory compliance (page 2), added Intended use statement in section 4.3 Electromagnetic interference (EMI), updated legal statement in cover page and added Documentation feedback e-mail address in contacts page.
R05	25-Feb-2019	rmak	Added information on EXTINT0 pin usage as a generic PIO13 in Section 1.5.2 and in Table 2. Updated Table 8.
R06	05-May-2020	mala, dama	Added section Layout design-in: Thermal management in Chapter 2. Updated document information section for LEA-M8T-1-00 product.
R07	18-Jan-2023	vema	Firmware version to TIM 1.12 for LEA-M8T-1-01

Contact

u-blox AG

Address: Zürcherstrasse 68
8800 Thalwil
Switzerland

For further support and contact information, visit us at www.u-blox.com/support.